

S-MFC3.1

FCOS Package
For contact based Memory ICs (Data carrier etc.)

Short Product Overview

May 2010

Chip Card & Security



S-MFC3.1 Short Product Overview		Ref.: Chip_Card_Product_Overview_11/09
Revision History: Current Version 05.10		
Previous Releases:		
Page		

Important: Further information is confidential and on request. Please contact:

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Edition 2010
Published by Infineon Technologies AG,
Chip Card & Security
81726 Munich, Germany
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Product name	S-MFC3.1	
Picture		
Product description	Contact based module 6 Contacts FCOS ™ technology PET Tape Flip Chip	
Typical Applications	Healthcare, Ticketing, Loyalty, Access Control	
Pitch	9.5 mm	
Dimensions	11 x 8.3 mm	
Thickness	max. 538µm	
Contact Surface	NiAu	
Delivery form	Tape on Reel Reel diameter 330mm	
ISO - reference	ISO/IEC 7810 SO/IEC 7816-1 ISO/IEC 10373-1 / -3	
Derivatives	S-MFC3.1-6-1, Au surface S-MFC1.6-6-1, Ni coating	

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